

09/365,356

L Number	Hits	Search Text	DB	Time stamp
1	781	(438/118).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/27 12:22
2	528	((438/118).CCLS.) and @ad<19990730	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/27 12:22
3	130	((438/118).CCLS.) and @ad<19990730) and strip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/27 12:23
4	26	((438/118).CCLS.) and @ad<19990730) and (strip near6 adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/27 12:52
5	915	(257/701).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/27 12:53
6	776	((257/701).CCLS.) and @ad<19990730	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/27 12:53
7	189	((257/701).CCLS.) and @ad<19990730) and adhesive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/27 12:54
8	2	((257/701).CCLS.) and @ad<19990730) and (adhesive near6 strip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/27 12:55
9	242	((adhesive near6 strip) near6 double)and @ad<19990730 and (semiconductor or chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/27 12:58
10	50	((adhesive near6 strip) near6 double)and @ad<19990730 and (semiconductor or chip or die)) and package	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/27 12:58